

## ABSTRACT OF THE DISCLOSURE

A stacked package for electronic elements is provided, a plurality of stud bumps are formed on a substrate by means of a stud bump process to align with a plurality of vias of one provided electronic element. The stud bumps respectively pass through the vias and  
5 electrically connect the electronic element. Furthermore, additional electronic elements are stacked on the carrier according to a similar way to form a stacked electronic package.